4

FEF HOME | SEARCH IEEE | SHOP | WEB ACCOUNT | CONTACT IEEE

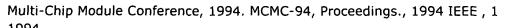
Membership Public	ations/Services Standards Co	onferences Careers/Jobs
IEEE /	Xplore®	Welcome United States Patent and Trademark O
Help FAQ Terms IE Review Welcome to IEEE Xplore - Home	Your search matched 16 of 93: Results are shown 15 to a page	* Se 3812 documents. c, sorted by publication year in descending order.
O- What Can I Access? O- Log-out	Results: Journal or Magazine = JNL Co	onference = CNF Standard = STD
Tables of Contents - Journals & Magazines - Conference Proceedings - Standards	approaching atomic on Thomas, M.E.; Smith, L.	ations in porous low k and metal interconnect s limensions D.M.; Wallace, S.; Iwamoto, N.; y Conference, 2002. Proceedings of the IEEE 2002
Search By Author Basic Advanced Member Services Join IEEE Establish IEEE Web Account Access the IEEE Member Digital Library Print Format	2 Precision electrical Babcock, J.A.; Francis, Dhayagude, T.; Yindeep Egan, K.; Bergemont, A	tters , Volume: 21 Issue: 6 , Jun 2000
	3 Atmospheric therm Barnes, N.P.; Thomas, Quantum Electronics, II Page(s): 962 -969	al lensing in laser resonators M.E.; Koch, G.J.; Marsh, W.B.; EEE Journal of, Volume: 31 Issue: 5, May 1995 ext (712 KB)] IEEE JNL
	Saadat, I.A.; Thomas, I	turing Strategy With Wafer Cost Estimation M.E.; Gattiker, A.; Maly, W.; Sturing, 1994. Extended Abstracts of ISSM '94. 1994

[Abstract] [PDF Full-Text (452 KB)] **IEEE CNF**

Page(s): 57 -60

5 Are there any alternatives to " known g od die" ? [MC Gattiker, A.E.; Maly, W.; Thomas, M.E.;

۴



Page(s): 102 -107

[Abstract] [PDF Full-Text (540 KB)] IEEE CNF

6 Extraction of defect size distributions in an IC layer using test strudata

Khare, J.B.; Maly, W.; Thomas, M.E.;

Semiconductor Manufacturing, IEEE Transactions on , Volume: 7 Issue: 3 , A

Page(s): 354 -368

[Abstract] [PDF Full-Text (1360 KB)] IEEE JNL

7 Smart-substrate multichip-module systems

Maly, W.; Feltham, D.B.I.; Gattiker, A.E.; Hobaugh, M.D.; Backus, K.; Thom Design & Test of Computers, IEEE, Volume: 11 Issue: 2, Summer 1994 Page(s): 64-73

[Abstract] [PDF Full-Text (836 KB)] IEEE JNL

8 Extraction of defect characteristics for yield estimation using the d bridge test structure

Khare, J.B.; Daniels, B.J.; Campbell, D.M.; Thomas, M.E.; Maly, W.; VLSI Technology, Systems, and Applications, 1991. Proceedings of Technical 1991 International Symposium on , 22-24 May 1991

Page(s): 428 -432

[Abstract] [PDF Full-Text (452 KB)] IEEE CNF

9 Multilevel microcoaxial interconnect: a novel technology for VLSI microwave circuits

Thomas, M.E.; Saadat, I.A.; Sekigahama, S.;

VLSI Multilevel Interconnection Conference, 1991, Proceedings., Eighth Inter

IEEE , 11-12 Jun 1991

Page(s): 116 -122

[Abstract] [PDF Full-Text (768 KB)] IEEE CNF

10 VLSI multilevel micro-coaxial interconnects for high speed device:

Thomas, M.E.; Saadat, I.A.; Sekigahama, S.;

Electron Devices Meeting, 1990. Technical Digest., International , 9-12 Dec 1990

Page(s): 55 -58

[Abstract] [PDF Full-Text (304 KB)] IEEE CNF

11 Issues associated with the use of electroless copper films for submultilevel interconnections

Thomas, M.E.; Sekigahama, S.; Myers, S.A.;

VLSI Multilevel Interconnection Conference, 1990. Proceedings., Seventh Int

IEEE , 12-13 Jun 1990

Page(s): 335 -337

[Abstract] [PDF Full-Text (428 KB)] IEEE CNF

12 The mechanical planarization of interlevel dielectrics for multileve interconnect applications

Thomas, M.E.; Sekigahama, S.; Renteln, P.; Pierce, J.M.; VLSI Multilevel Interconnection Conference, 1990. Proceedings., Seventh Int IEEE, 12-13 Jun 1990

Page(s): 438 -440

[Abstract] [PDF Full-Text (180 KB)] IEEE CNF

13 Characterization of mechanical planarization processes

Renteln, P.; Thomas, M.E.; Pierce, J.M.;

VLSI Multilevel Interconnection Conference, 1990. Proceedings., Seventh Int IEEE , 12-13 Jun 1990

Page(s): 57 -63

[Abstract] [PDF Full-Text (324 KB)] IEEE CNF

14 An advanced single-level polysilicon submicrometer BiCMOS techr Brassington, M.P.; El-Diwany, M.H.; Razouk, R.R.; Thomas, M.E.; Tuntasooa Electron Devices, IEEE Transactions on , Volume: 36 Issue: 4 , Apr 1989 Page(s): 712 -719

[Abstract] [PDF Full-Text (1072 KB)] IEEE JNL

15 The potential of using refractory metals and barrier layers to gene temperature interconnects

Thomas, M.E.; Hartnett, M.P.; McKay, J.E.; Kapoor, A.K.; Chinn, J.D.; VLSI Multilevel Interconnection Conference, 1988. Proceedings., Fifth InternIEEE, 13-14 Jun 1988

Page(s): 183 -190

[Abstract] [PDF Full-Text (540 KB)] IEEE CNF

1 <u>2 [Next]</u>

Home | Log-out | Journals | Conference Proceedings | Standards | Search by Author | Basic Search | Advanced Search | Join IEEE | Web Account | New this week | OPAC Linking Information | Your Feedback | Technical Support | Email Alerting No Robots Please | Release Notes | IEEE Online Publications | Help | FAQ| Terms | Back to Top

Copyright © 2003 IEEE - All rights reserved